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**FINAL PRODUCT/PROCESS CHANGE NOTIFICATION**  
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**02 Dec 2009**

**SUBJECT: ON Semiconductor Final Product/Process Change Notification #16368**

**TITLE: Piestany to Oudenaarde Wafer Fabrication Transfer for NCV7708B**

**PROPOSED FIRST SHIP DATE: 02 Mar 2010**

**AFFECTED CHANGE CATEGORY(S): Manufacturing Transfer (wafer fabrication)**

**AFFECTED PRODUCT DIVISION: APRG**

**QUESTIONS CONCERNING THIS NOTIFICATION:**

Contact your local ON Semiconductor Sales Office or Peter Lanyon <[Peter.Lanyon@onsemi.com](mailto:Peter.Lanyon@onsemi.com)>

**SAMPLES:**

Contact your local ON Semiconductor Sales Office or Peter Lanyon <[Peter.Lanyon@onsemi.com](mailto:Peter.Lanyon@onsemi.com)>

**ADDITIONAL RELIABILITY DATA:**

Contact your local ON Semiconductor Sales Office or Peter Turlo <[Peter.Turlo@onsemi.com](mailto:Peter.Turlo@onsemi.com)>

**NOTIFICATION TYPE:**

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

**DESCRIPTION AND PURPOSE:**

Transfer of device wafer fabrication operation from ON Semiconductor, Piestany to ON Semiconductor, Oudenaarde. Purpose of the transfer is to consolidate manufacturing operations.

The ON Semiconductor part number will be changed to NCV7708BDWR2G.


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**RELIABILITY DATA SUMMARY:**

Test	Ref	Test Conditions	End Points	Note	Lot A	Lot B	Lot C	Results
<b>Electrical Test</b>	ON Data Sheet	ON Product Specification	See Below	All Devices				
<b>ELFR</b>	JA108	Ta = 135°C <b>24 hrs</b>	Test @ R H		1600	2000	800	<b>0 / 4400</b>
Dynamic <b>HTOL</b>	JA108	High Temp Operational Life: Tj = 150°C for <b>504 hrs</b>	Test @ R H <b>c=0</b>		168	144	168	
		T168			ok	ok	ok	Pass
		<b>T504</b>			<b>ok</b>	<b>ok</b>	pending	Two Lots <b>Pass</b> Lot C data pending
		T1008 - fyi		FYI only	ok	ok	pending	
		T1440 - fyi		FYI only	ok	pending	pending	
<b>HTSL</b>	J103	High Temp Storage Life: Ta = 175°C for <b>500 hrs</b>	Test @ R H <b>c=0</b>		80	80	80	
		<b>T500</b>						<b>0 / 240</b>
		T1000 - fyi		FYI only				<b>0 / 240</b>
		T2000 - fyi		FYI only				<b>0 / 240</b>
<b>PC</b>	JA112 J113	Moisture Pre-conditioning for AC, TC, THB, SAT	Test @ R(H)		All	All	All	MSL3/ 260°C
<b>SAT</b>	12MSB17722C	Scanning Acoustic Tomography			5	5	5	No Delamination.
<b>THB</b>	JA104	Temp Humidity Bias: 85°C/85% RH, bias for <b>1000 hrs</b>	Test @ R H <b>c=0</b>		80	80	80	
		T500						<b>0 / 240</b>
		<b>T1000</b>						<b>0 / 240</b>
<b>AC</b>	JA102	Autoclave: 121°C/100%RH, 15 psig, <b>96 hrs</b>	Test @ R <b>c=0</b>		80	80	80	<b>0 / 240</b>
<b>TC</b>	JA104	Temperature Cycle: -65°C to +150°C; for <b>500 cycles</b> .	Test @ R H <b>c=0</b>		80	80	80	<b>0 / 240</b>
<b>WBP</b>	M2011	Wire Bond Pull Strength, Condition C. After TC500	<b>3gm</b> Pull Force Min	30 bonds from 5 units	5			<b>Pass</b>
<b>DPA</b>	AEC-Q101	Destructive Physical Analysis Post TC500			5	5	5	<b>Pass</b>
<b>PD</b>	JB100	Per case outline	<b>Cpk &gt;1.33</b>		30	30	30	<b>Pass. Cpk&gt;1.33</b> In-line data
<b>SD</b>	JESD22- B102	Solderability	<b>&gt;95% coverage</b>		15	15	15	<b>0 / 45</b>
<b>WBP</b>	M2011	Wire Bond Pull Strength, Condition C.	<b>Cpk &gt;1.33</b>		30	30	30	<b>Pass. Cpk&gt;1.33</b> In-line data
<b>BS</b>	AEC-Q100-001	Bond Shear Test	<b>Cpk &gt;1.33</b>	30 bonds from 5 units	30	30	30	<b>Pass. Cpk&gt;1.33</b> In-line data
<b>ESD</b>	AEC-Q100-002 AEC-Q100-003 AEC-Q100-011	Human Body Model (HBM) and Machine Model (MM) Charge Device Model (CDM)	Test @ R H	3 units/V level per Model	192			HBM <b>4.0kV</b> MM <b>200V</b> CDM <b>1kV</b>
<b>LU</b>	JESD 78	Dynamic Latch-up	Test @ R H <b>c=0</b>		6			<b>0 / 6</b> (Class II-Level A)
<b>ED</b>	ON Data Sheet	Electrical Distributions	<b>Cpk &gt; 1.67</b>		30	30	30	<b>Cpk &gt; 1.67</b>

Qualification points in **bold**.

**AFFECTED DEVICE LIST**

NCV7708ADWR2G